

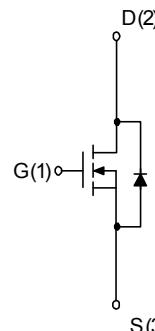
N-Channel Enhancement Mode MOSFET

Features

- 100V/73A,
- $R_{DS(ON)} = 9.6\text{m}\Omega(\text{max.}) @ V_{GS} = 10\text{V}$
- $R_{DS(ON)} = 12.4\text{m}\Omega(\text{max.}) @ V_{GS} = 4.5\text{V}$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available
(RoHS Compliant)

Pin Description

Top View of TO-251S



N-Channel MOSFET

Applications

- Power Management for SMPS.
- DC-DC Converter.

Ordering and Marking Information

SM1A63NH	□□□-□□□	Assembly Material	Package Code
		Handling Code	UC : TO-251S
		Temperature Range	Operating Junction Temperature Range
		Package Code	C : -55 to 150 °C
SM1A63NH UC :  SM1A63NH		Handling Code TU : Tube	
		Assembly Material G : Halogen and Lead Free Device	
XXXXX		XXXXX - Lot Code	

Note : SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

SINOPOWER reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit	
Common Ratings				
V_{DSS}	Drain-Source Voltage	100	V	
V_{GSS}	Gate-Source Voltage	± 20		
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150		
I_S	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	36	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	73	A
		$T_C=100^\circ\text{C}$	46	
I_{DM}^a	Pulsed Drain Current	$T_C=25^\circ\text{C}$	292	
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	104	W
		$T_C=100^\circ\text{C}$	41	
$R_{\theta JC}$	Thermal Resistance-Junction to Case		1.2	$^\circ\text{C}/\text{W}$
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	11.4	A
		$T_A=70^\circ\text{C}$	9.1	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	2.5	W
		$T_A=70^\circ\text{C}$	1.6	
R_{QJA}^c	Thermal Resistance-Junction to Ambient		50	$^\circ\text{C}/\text{W}$
I_{AS}^b	Avalanche Current, Single pulse	$L=0.5\text{mH}$	25	A
E_{AS}^b	Avalanche Energy, Single pulse	$L=0.5\text{mH}$	156	mJ

Note a : Pulse width limited by max. junction temperature.

Note b : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_j=25^\circ\text{C}$).

Note c : Surface Mounted on 1in² pad area.

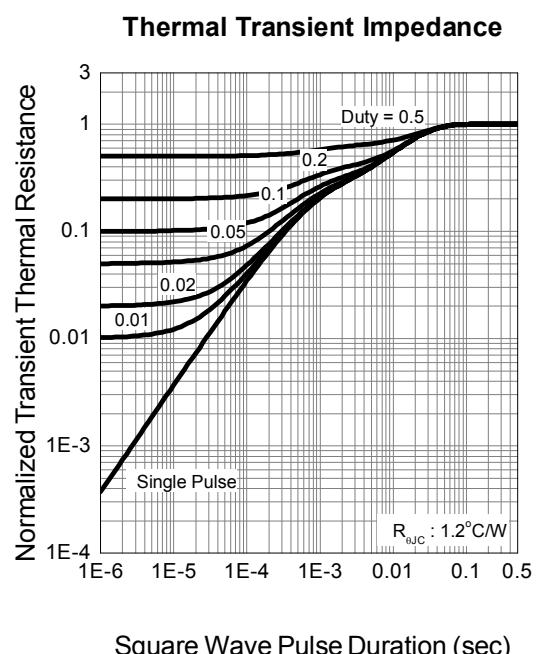
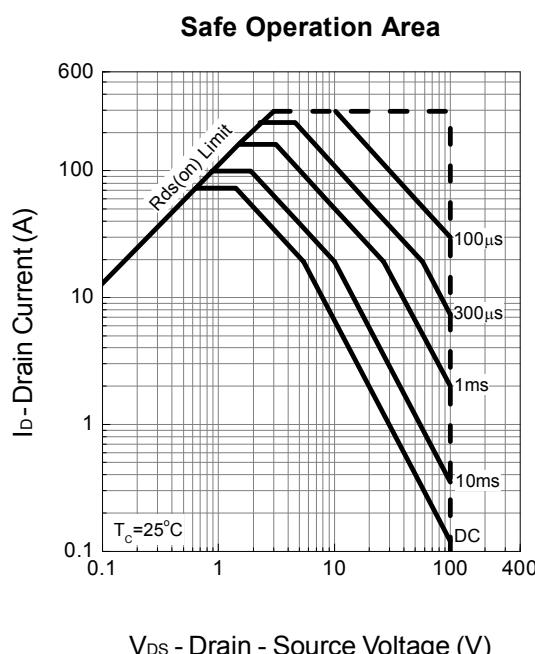
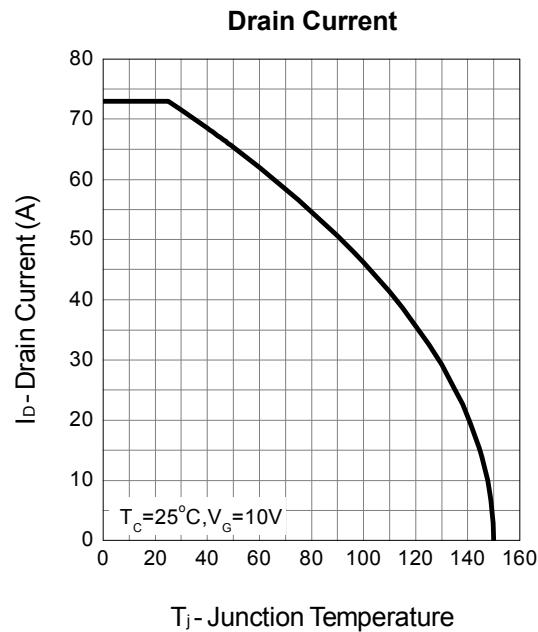
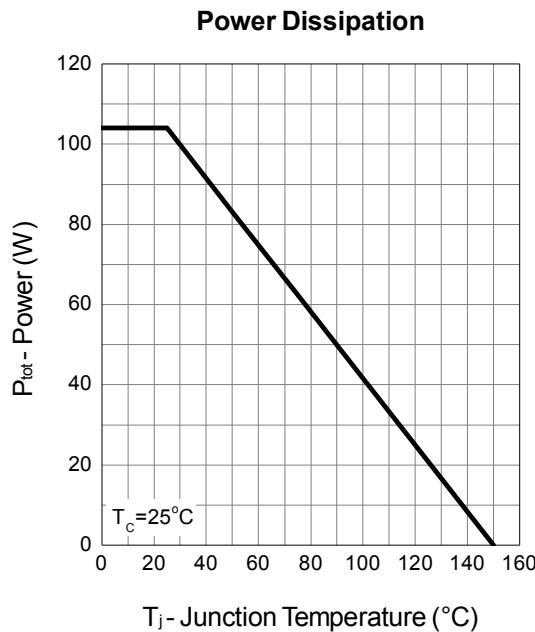
Electrical Characteristics (T_A = 25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1	2	3	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^d	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =30A	-	8	9.6	mΩ
		V _{GS} =4.5V, I _{DS} =20A	-	9.5	12.4	mΩ
Diode Characteristics						
V _{SD} ^d	Diode Forward Voltage	I _{SD} =30A, V _{GS} =0V	-	0.8	1.3	V
t _{rr}	Reverse Recovery Time	I _{SD} =30A, dI _{SD} /dt=100A/μs	-	52	-	ns
Q _{rr}	Reverse Recovery Charge		-	105	-	nC
Dynamic Characteristics ^e						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	1.0	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, Frequency=1.0MHz	-	2310	3010	pF
C _{oss}	Output Capacitance		-	690	-	
C _{rss}	Reverse Transfer Capacitance		-	50	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =30V, R _L =30Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	20	36	ns
t _r	Turn-on Rise Time		-	8	15	
t _{d(OFF)}	Turn-off Delay Time		-	49	89	
t _f	Turn-off Fall Time		-	66	119	
Gate Charge Characteristics ^e						
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =4.5V, I _{DS} =30A	-	23	-	nC
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =10V, I _{DS} =30A	-	47	66	
Q _{gs}	Gate-Source Charge		-	9	-	
Q _{gd}	Gate-Drain Charge		-	9	-	

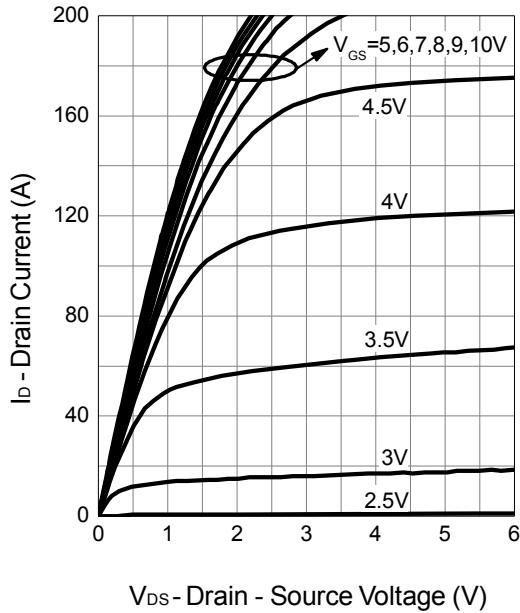
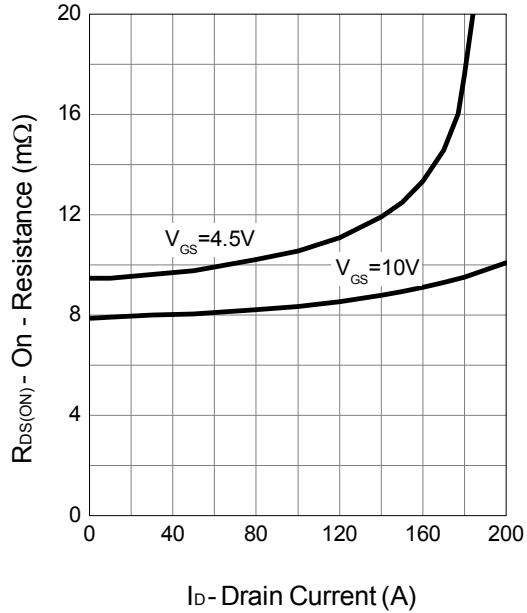
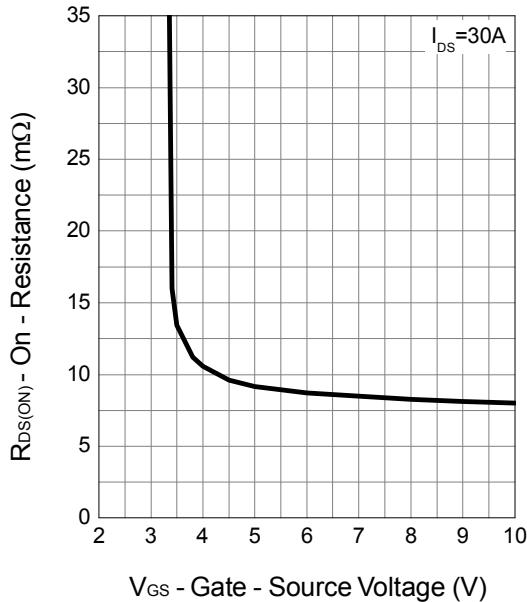
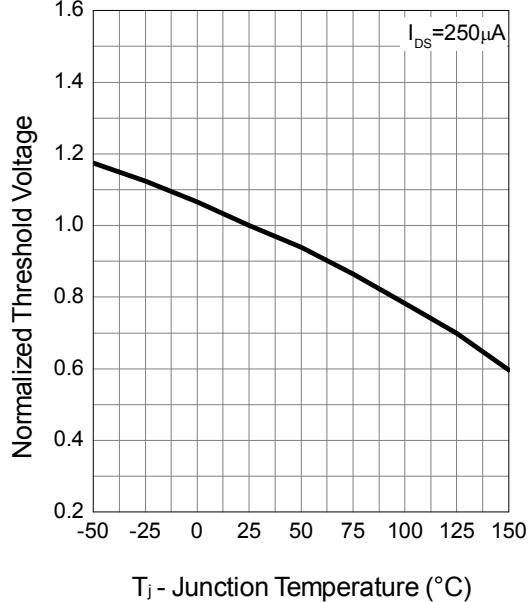
Note d : Pulse test ; pulse width≤300μs, duty cycle≤2%.

Note e : Guaranteed by design, not subject to production testing.

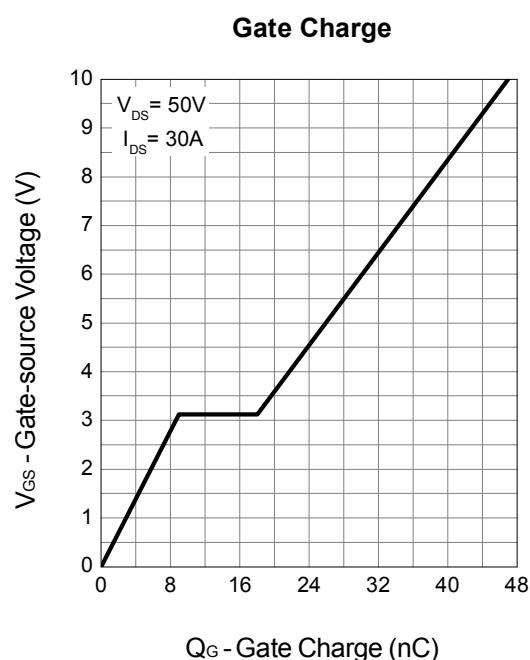
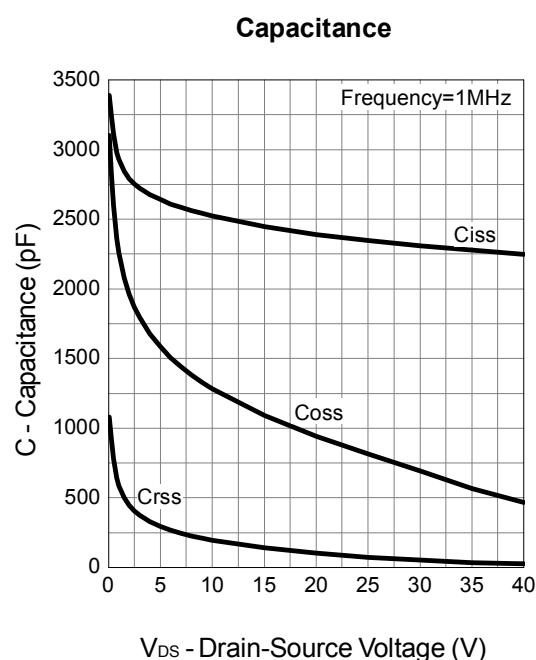
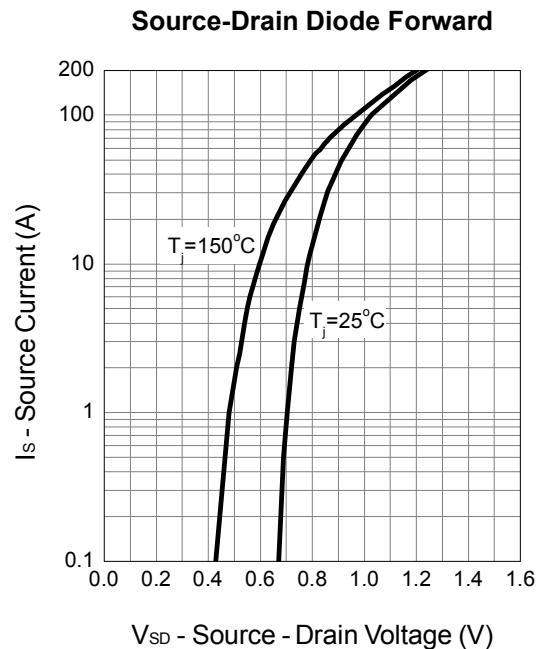
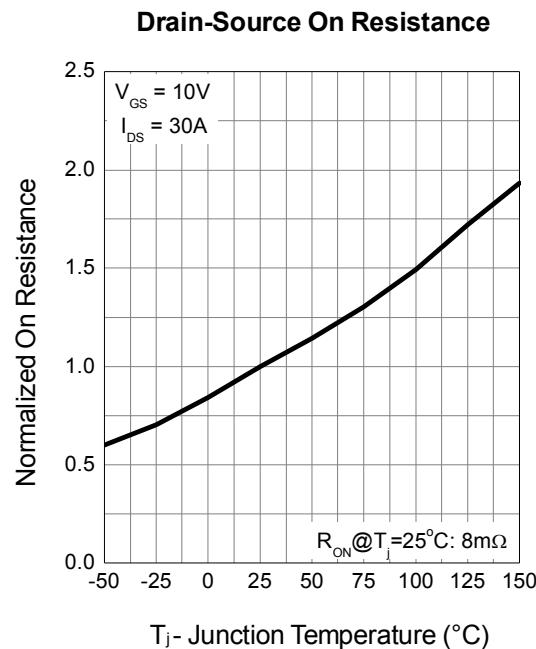
Typical Operating Characteristics



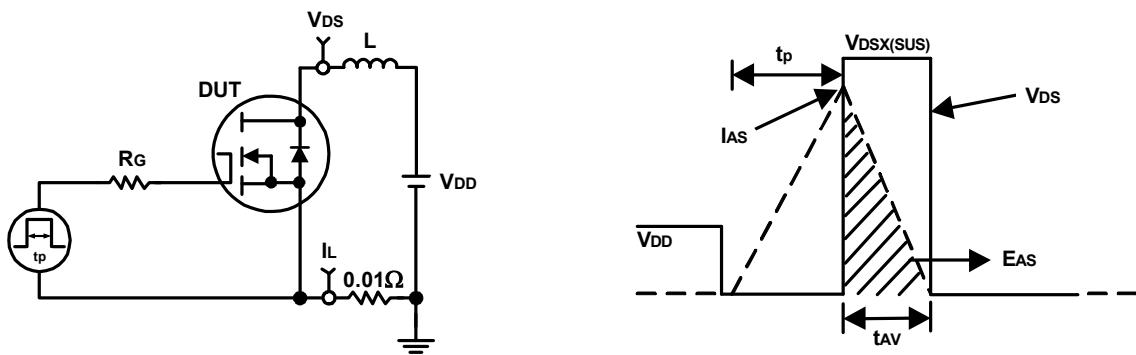
Typical Operating Characteristics (Cont.)

Output Characteristics**Drain-Source On Resistance****Gate-Source On Resistance****Gate Threshold Voltage**

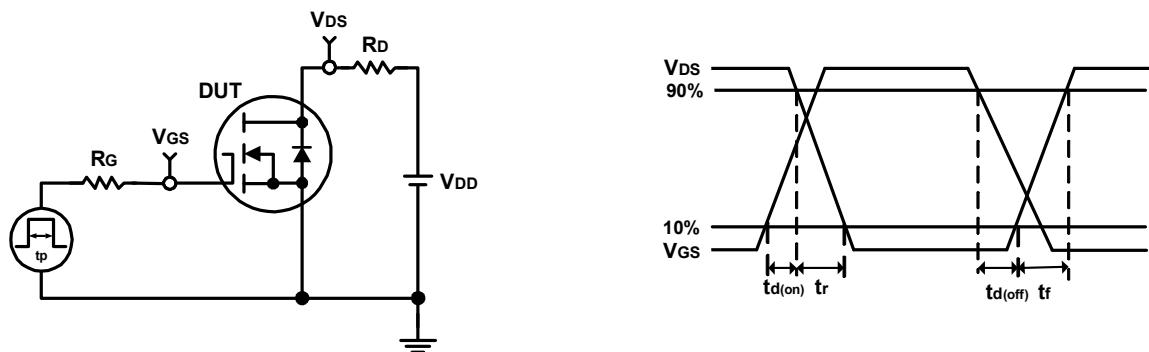
Typical Operating Characteristics (Cont.)



Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



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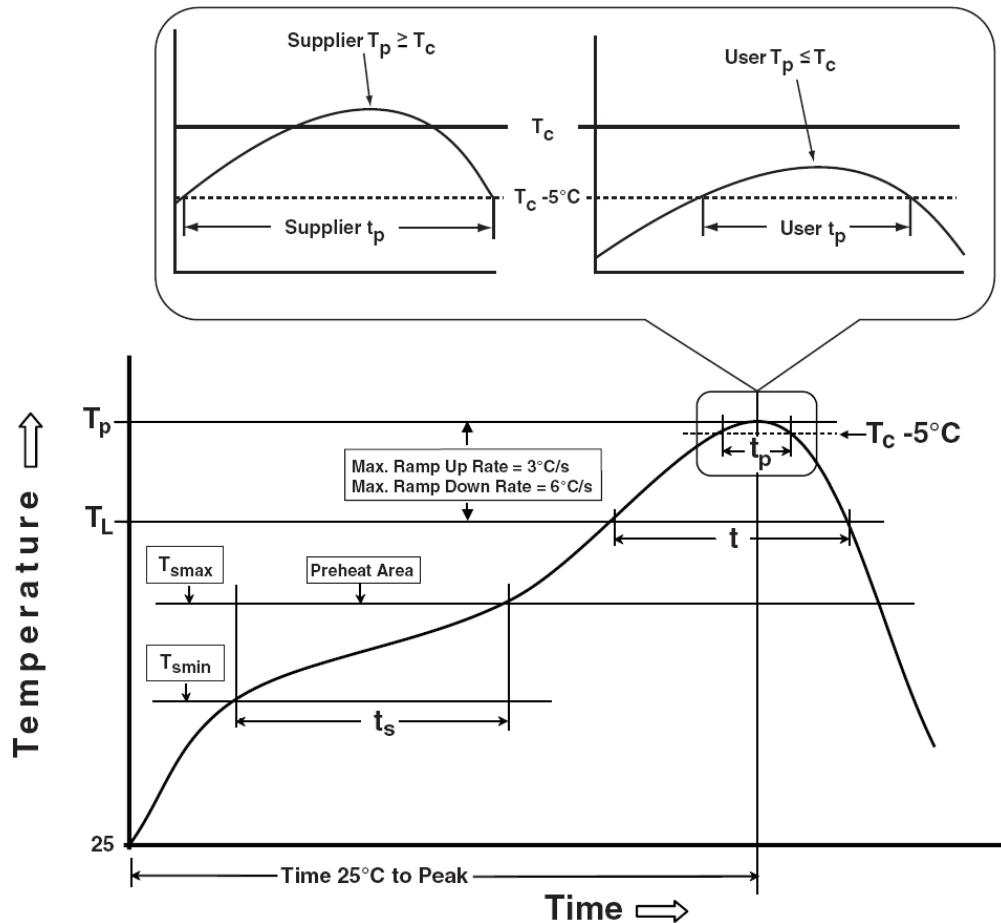
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Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{smin})	100 °C	150 °C
Temperature max (T_{smax})	150 °C	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.

* Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum.
 ** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Table 1. SnPb Eutectic Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ Tjmax
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ Tjmax
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

Customer Service

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